

INTERNATIONAL ELECTROTECHNICAL COMMISSION

IEC 61191-2
Edition 3.0 2017-05

PRINTED BOARD ASSEMBLIES –

**Part 2: Sectional specification –
Requirements for surface mount soldered assemblies**

C O R R I G E N D U M 1

Figure 5 – J lead joint

Replace, in the table, footnote f by footnote d, and delete footnote e.